Part Number : 1725018002
Product Description : zSFP+ Stacked Ganged Assembly with Metal Spring Fingers, 2-by-8, with Enhanced Airflow, 320 Circuits
Series Number : 172501
Status : Active
Product Category : High-Speed I/O Connectors

Documents and Resources

Drawings

1725018002_sd.pdf

EE-170071-0001-001.pdf

SP-170426-1000-001.zip

Specifications

PS-170071-0001-001.pdf

TS-170071-0001-001.pdf

Product Environment Compliance

Compliance

GADSL/IMDS	Compliant with Exemption 44; 34; 33
China RoHS	ⓔ per SJ/T 11365-2006
EU ELV	Not Relevant
Low-Halogen Status	Not Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2025)7771-DC (04 Feb 2026)
EU RoHS	Compliant per EU 2015/863

Compliance Statements

- EU RoHS
- REACH SVHC
- Low-Halogen

Industry Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

Substances of Interest

- PFAS

EU RoHS Certificate of Compliance

Additional Product Compliance Information

Part Details

General

Status	Active
Category	High-Speed I/O Connectors
Series	172501
Description	zSFP+ Stacked Ganged Assembly with Metal Spring Fingers, 2-by-8, with Enhanced Airflow, 320 Circuits
Application	Module-to-Board
Component Type	Receptacle
Product Name	zSFP Plus,zSFP+
Type	Pluggable
UPC	889056079679

Agency

UL	E29179

Electrical

Current - Maximum per Contact	0.5A
Data Rate	28.0 Gbps
Shielded	Yes
Shield Type	EMI Fingers
Voltage - Maximum	30V AC (RMS)/DC

Physical

Circuits (Loaded)	320
Color - Resin	Black
Durability (mating cycles max)	100
Flammability	94V-0
Gender	Female
Lock to Mating Part	Yes
Material - Metal	High Performance Alloy (HPA)
Material - Plating Mating	Gold
Material - Plating Termination	Matte Tin
Material - Resin	High Performance Thermoplastic
Net Weight	153.860/g
Number of Rows	2
Orientation	Right Angle
Packaging Type	Tray
Panel Mount	No
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness - Recommended	1.57mm
PC Tail Length	1.70mm
Pitch - Mating Interface	0.80mm
Pitch - Termination Interface	0.80mm
Plating min - Mating	0.762µm
Plating min - Termination	0.762µm
Polarized to Mating Part	Yes
Polarized to PCB	Yes
Ports	16
Temperature Range - Operating	-40° to +85°C
Termination Interface Style	Through Hole - Compliant Pin

Solder Process Data

Lead-Free Process Capability	N/A